

CERTIFICATE

The Certification Body of TÜV SÜD PSB Pte Ltd

certifies that

STATS CHIPPAC PTE. LTD.

5 Yishun Street 23 Singapore 768442

has established and applies a Quality Management System for

- 1. Design and Development of ICs Package and Test Hardware and Software
- 2. Wafer Sort, Wafer Process, Assembly and Testing of Integrated Circuit Packages
- 3. Packages WLCSP (Wafer Level Chip Scale Packages), Bump and Integrated Passive Device and eWLB (Embedded Wafer Level Ball Grid Array)
- 4. Packages WLD-CIS (Wafer Level Device CMOS Image Sensor)
 (See Appendix to Certificate for Details)

Proof has been furnished that the requirements according to

ISO 9001: 2015

are fulfilled. The certificate is valid from 2021-08-01 to 2024-07-31

Certificate Registration No. 96-2-0622

Date of Print: 2021-08-03





SIEW Kwai Heng, Tiffany Head of Certification Body Management Systems Business Assurance Division



Page 1 of 2

Please refer to <u>www.tuvsud.com/en-sg</u> for current certificate status in the "Directory of Management System Certified Companies".



APPENDIX

To Certificate Number: 96-2-0622

Issue Number: 1

Date of Print: 2021-08-03

Issued to: STATS CHIPPAC PTE. LTD.

5 Yishun Street 23 Singapore 768442

Process or service in respect of which the company is Certified:

- 1. Design and Development of ICs Package and Test Hardware and Software
- 2. Wafer Sort, Wafer Process, Assembly and Testing of Integrated Circuit Packages
- 3. Packages WLCSP (Wafer Level Chip Scale Packages), Bump and Integrated Passive Device and eWLB (Embedded Wafer Level Ball Grid Array)
- 4. Packages WLD-CIS (Wafer Level Device CMOS Image Sensor)

Process Detail(s)/Location(s):

The scope of certification also covers the following remote location:

Location	Scope of Certification
STATS CHIPPAC PTE. LTD.	Testing of Integrated Circuit Packages
507/509 Yishun Industrial Park A Singapore 768734	





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Page 2 of 2